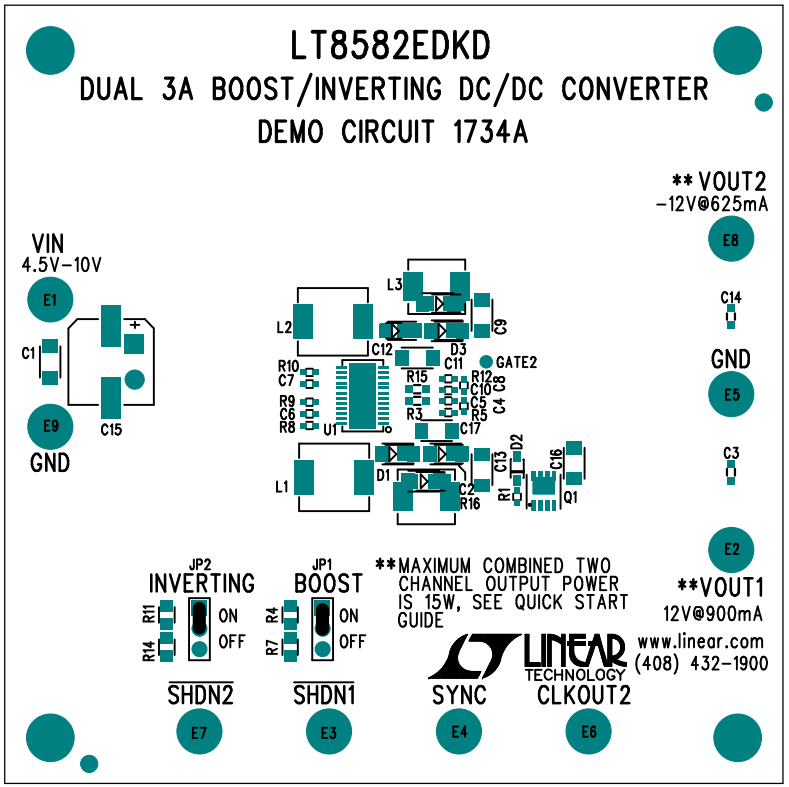
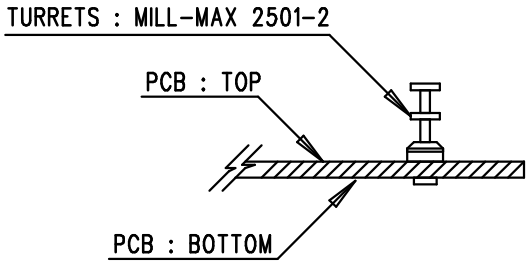
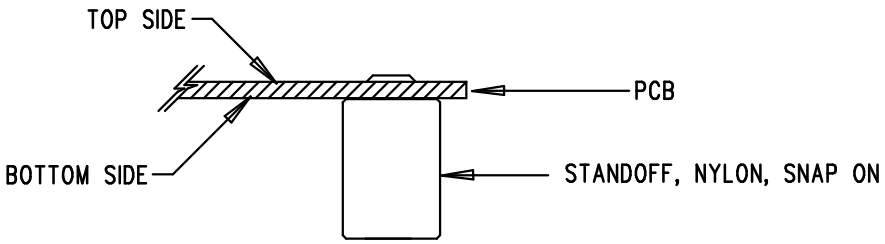
REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
–	3	PRODUCTION	MEHDI A.	8-22-11



NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.





APPROVALS	
PCB DES.	JW
APP ENG.	MEHDI A.
SCALE = NONE	

LINEAR TECHNOLOGY
1630 MCCARTHY BLVD
MILPITAS, CA 95035
PH: (408)432-1900
www.linear.com
LTC CONFIDENTIAL-
FOR CUSTOMER USE ONLY

TITLE: TOP ASSEMBLY DRAWING
DUAL 3A BOOST/INVERTING DC/DC CONVERTER

SIZE	IC NO.	REV.
N/A	LT8582EDKD DEMO CIRCUIT 1734A	3

FILENAME: DC1734A-3.PCB